US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB US-PGP	/12/30 9 /08/21 4 /01/23 1
EPO; JPO; DERWENT; IBM_TDB USPAT; 2003/ US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2003/ US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2002/ DERWENT; IBM_TDB USPAT; 2002/ DERWENT; IBM_TDB USPAT; 2002/ DERWENT; IBM_TDB USPAT; 2002/ DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; 2003/ DERWENT; IBM_TDB USPAT; 2003/ DERWENT; IBM_TDB USPAT; 2003/ DERWENT; IBM_TDB USPAT; IBM_TDB	/12/30 9 /08/21 4 /01/23 1
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; Integrated circuit' US-PGPUB; EPO; JPO; DERWENT; IBM_TDB US-PGPUB; INTEGRATED US-PGPUB; INTE	708/21 4 701/23 1 708/21
- 2054 (438/612).ccls. or (438/597).ccls. and (USPĀT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; Integrated circuit' US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPĀT; US-PGPUB; INTEGRATED USPĀT; IBM_TDB USPĀT; IBM_T	708/21 4 701/23 1 708/21
@ad<=20020109 Gad<=20020109	708/21 4 701/23 1 708/21
DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; Integrated circuit' EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	1 /01/23 l /08/21
- 337 ((438/612).ccls. or (438/597).ccls. and (BM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; INTEGRATED USPAT; IBM_TDB	1 /01/23 l /08/21
Qad<=20020109) and copper and aluminum	1 /01/23 l /08/21
T4 ((438/612).ccls. or (438/597).ccls. and (BPO; JPO; DERWENT; IBM_TDB (USPAT; US-PGPUB; Integrated circuit' EPO; JPO; DERWENT; IBM_TDB (USPAT; IBM_TDB) (438/612).ccls. or (438/597).ccls. and USPAT; 2002/	/01/23 l /08/21
Total (438/612).ccls. or (438/597).ccls. and (438/612).ccls. or (438/612).ccls. or (438/597).ccls. and (438/612).ccls. or (43	/08/21
- 74 ((438/612).ccls. or (438/597).ccls. and (USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2002/	/08/21
@ad<=20020109) and 'bonding pad' with US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; 2002/	/08/21
'integrated circuit'	
1 ((438/612).ccls. or (438/597).ccls. and USPAT; 2002/	
1 10 1,000001001 1 2 11 11 11 11 11 11 11 11 11 11 11 1	
@ad<=20020109) and Cu adj bonding adj pad US-PGPUB; 11:13 with 'integrated circuit' EPO; JPO;	3
With Threegrated Circuit DERWENT;	
IBM_TDB	/00/01
- 6 ((438/612).ccls. or (438/597).ccls. and USPAT; 2002/ @ad<=20020109) and Copper adj bonding adj US-PGPUB; 11:14	/08/21 4
pad , EPO; JPO;	
DERWENT;	-
	/12/22
with 'IMD' or 'intermetal dielectric' US-PGPUB; 12:10)
EPO; JPO; DERWENT;	
IBM TDB	,
- 0 @ad<=20020109 and cu adj 'bonding pad' USPAT; 2002/ with 'IMD' US-PGPUB; 11:27	/08/21 7
EPO; JPO;	
DERWENT;	
- 0 @ad<=20020109 and cu adj 'bonding pad' USPAT; 2003/	/12/22
with 'intermetal dielectric' US-PGPUB; 12:00) .
DERWENT;	
IBM TDB	/01/22
- 6 @ad<=20020109 and cu adj 'bonding pad' USPAT; 2003/ with 'Al' US-PGPUB; 09:03	/01/23 3
EPO; JPO;	
DERWENT;	
3 @ad<=20020109 and cu adj 'bonding pad' USPAT; 2002/	/08/21
and 'IMD' US-PGPUB; 11:43 EPO; JPO;	3
DERWENT;	
IBM_TDB	/09/21
- 1 "3942245".PN. USPĀT 2002/	/08/21 0
_ 1 "5075965".PN. USPAT 2002/	/08/21
11:40 - 1 "5288006".PN. USPAT 2002/	0 /08/21
11:40	0
- 1 "5376235".PN. USPAT 2002/	/08/21 1
- 1 "5384284".PN. USPAT 2002/	/08/21
11:41 1 "5426412" DN USDAT 2002	1 /08/21
- 1 "5436412".PN. USPAT 2002/	

-	0	@ad<=20020109 and copper adj bonding adj pad with 'intermetal dielectric'	USPAT; US-PGPUB;	2003/12/23 09:52
			EPO; JPO; DERWENT;	
_	4	@ad<=20020109 and copper adj bonding adj pad and 'intermetal dielectric'	IBM_TDB USPAT;	2002/08/21
		pad and intermetal dielectric	US-PGPUB; EPO; JPO; DERWENT;	11:46
	809	(228/180.21).CCLS.	IBM_TDB USPAT;	2002/09/21
		(220) 100.21) .CCLS.	US-PGPUB; EPO; JPO;	2002/08/21 11:48
			DERWENT; IBM TDB	
_	. 93	((228/180.21).CCLS.) and bonding adj pad	USPAT; US-PGPUB;	2002/08/21 11:50
			EPO; JPO; DERWENT;	11.50
	9	((228/180.21).CCLS.) and bonding adj pad	IBM_TDB USPAT;	2002/08/21
		with copper	US-PGPUB; EPO; JPO;	13:32
			DERWENT; IBM TDB	
-	8	((228/180.21).CCLS.) and bond adj pad with copper	USPAT; US-PGPUB;	2002/08/21 13:30
			EPO; JPO; DERWENT;	10.00
_	0	((228/180.21).CCLS.) and bond adj pad	IBM_TDB USPAT;	2003/01/23
		with copper with 'Al' adj buffer	US-PGPUB; EPO; JPO;	08:45
			DERWENT; IBM TDB	
_	0	((228/180.21).CCLS.) and bond adj pad with copper with 'Al'	USPĀT; US-PGPUB;	2002/08/21 13:31
			EPO; JPO; DERWENT;	
	639	@ad<=20010119 and bonding adj pad with	IBM_TDB USPAT;	2002/08/21
		copper	US-PGPUB; EPO; JPO;	13:36
	0.5.0		DERWENT; IBM_TDB	
-	359	@ad<=20010119 and bonding adj pad with copper and aluminum	USPAT; US-PGPUB;	2002/08/21 13:47
			EPO; JPO; DERWENT;	
_	30	@ad<=20010119 and copper adj bonding adj pad and aluminum	IBM_TDB USPAT; US-PGPUB;	2002/08/21 13:59
		pad and atunthum	EPO; JPO; DERWENT;	15.55
	839	@ad<=20010119 and bonding adj pad and	IBM_TDB USPAT;	2002/08/21
		aluminum and buffer	US-PGPUB; EPO; JPO;	14:00
			DERWENT; IBM TDB	
-	4120	'bonding pad' and apparatus	USPAT; US-PGPUB;	2002/08/21 15:03
			EPO; JPO; DERWENT;	
_	3573	((257/459) or (257/676) or (257/786) or	IBM_TDB USPAT;	2002/08/21
		(275/670) or (257/672)).CCLS.	US-PGPUB; EPO; JPO;	15:07
			DERWENT; IBM_TDB	

_	1779	(438/612).ccls. and @ad<=20020109	USPAT;	2003/01/23
			US-PGPUB; EPO; JPO;	08:47
			DERWENT;	
	1	bond adj pad with copper with 'Al' and	IBM_TDB	2002/01/22
_	1	bond adj pad with copper with Al and buffer'	USPAT; US-PGPUB;	2003/01/23
			EPO; JPO;	
			DERWENT; IBM TDB	
_	11		USPAT;	2003/01/23
		and 'buffer'	US-PGPUB; EPO; JPO;	08:54
			DERWENT;	ŀ
		(470 (40) 3 3 3 4 00000100	IBM_TDB	0000/01/00
_	284	(438/48).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/01/23
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1722	(438/614).ccls. and @ad<=20020109	USPAT;	2003/08/05
		·	US-PGPUB;	10:35
			EPO; JPO; DERWENT;	
	500	(0557/450)	IBM_TDB	
_	573	(257/459).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/08/05
			EPO; JPO;	
			DERWENT; IBM TDB	
-	1222	(257/784).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:37
			EPO; JPO; DERWENT;	
			IBM TDB	
-	1209	(257/786).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/08/05
			EPO; JPO;	10.33
			DERWENT; IBM TDB	
-	735	(257/781-782).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:40
	•		EPO; JPO; DERWENT;	
			IBM TDB	
	1392	(257/774).ccls. and @ad<=20020109	USPAT; US-PGPUB;	2003/01/23 11:44
			EPO; JPO;	
		,	DERWENT; IBM TDB	
_	1	'bond pad' with 'copper' with 'Al' and	USPĀT;	2003/01/23
		'buffer'	US-PGPUB;	08:55
			EPO; JPO; DERWENT;	
		11 12	IBM_TDB	2002/01/22
_	1	'bonding pad' with 'copper' with 'Al' and 'buffer'	USPAT; US-PGPUB;	2003/01/23
			EPO; JPO;	
			DERWENT; IBM TDB	
_	122	'bonding pad' with 'Cu' with 'Al'	USPAT;	2003/01/23
			US-PGPUB;	09:05
			EPO; JPO; DERWENT;	
		0-14 20020100 1 12 12 12 12 12 12	IBM_TDB	2002/01/22
_	117	<pre>@ad<=20020109 and 'bonding pad' with 'Cu' with 'Al'</pre>	USPAT; US-PGPUB;	2003/01/23
		··	EPO; JPO;	
			DERWENT; IBM TDB	
L	l		TDM IDD	L

-	6	@ad<=20020109 and cu adj 'bonding pad'	USPAT;	2003/01/23
		with 'Al'	US-PGPUB;	09:03
			EPO; JPO;	
			DERWENT;	
	3.7	0 1. 00000100 1.11 1.	IBM_TDB	0000 (00 (05
	117	@ad<=20020109 and 'bonding pad' with 'Cu'	USPAT;	2003/08/05
		with 'Al'	US-PGPUB;	11:18
			EPO; JPO;	
			DERWENT;	
	,	H4011001H PV	IBM_TDB	0000 (01 (00
-	1	"4811081".PN.	USPAT	2003/01/23
	,	WE 001 F 40 W PM	11abam	09:57
_	1	"5001542".PN.	USPAT	2003/01/23
	1	"6108212".PN.	Habam	09:57
_	1	6100212 .PN.	USPAT	2003/01/23
	1	".co.c.4120" DN	HCDAM	2003/01/23
-	1	"6064120".PN.	USPAT	09:58
1	246	 @ad<=20020109 and 'bonding pad' with	USPAT;	2003/01/23
-	240	'integrated circuit' and 'Cu' and 'Al'	US-PGPUB;	10:02
		Integrated critcuit and cu and Ar	EPO; JPO;	10.02
			DERWENT;	
			IBM TDB	
_	231	(257/784).ccls. and @ad<=20020109 and	USPAT;	2003/01/23
	231	(237/764).CCIS. and ead(=20020109 and Copper' and 'aluminum'	US-PGPUB;	10:38
		Cobbet and armittion	EPO; JPO;	10.30
			DERWENT;	
			IBM TDB	
_	2356	(438/612).ccls. or (438/597).ccls. and	USPAT;	2003/08/05
		@ad<=20020109	US-PGPUB;	10:34
			EPO; JPO;	
		•	DERWENT;	
			IBM TDB	
-	798	(228/180.21).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:35
			EPO; JPO;	
			DERWENT;	· ·
			IBM TDB	
-	2531	(438/613-617).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:38
			EPO; JPO;	
			DERWENT;	İ
		·	IBM_TDB	
-	586	(257/459).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:39
			EPO; JPO;	
		·	DERWENT;	
	1000	(257/704)	IBM TDB	2002/22/25
-	1320	(257/784).ccls. and @ad<=20020109	USPAT;	2003/08/05
1			US-PGPUB;	10:40
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1288	(257/786).ccls. and @ad<=20020109	USPAT;	2003/08/05
	1200	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	US-PGPUB;	10:42
			EPO; JPO;	10.12
		•	DERWENT;	
			IBM TDB	
***	782	(257/781-782).ccls. and @ad<=20020109	USPAT;	2003/08/05
		,	US-PGPUB;	10:44
			EPO; JPO;	
		,	DERWENT;	
			IBM TDB	
-	1782	(257/676).ccls. and @ad<=20020109	USPAT;	2003/08/05
			US-PGPUB;	10:46
			EPO; JPO;	
			DERWENT;	
	·		IBM TDB	

-	27	@ad<=20020109 and 'bonding pad' near3 'Cu' with 'Al'	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/05 11:19
-	63	<pre>@ad<=20020109 and 'bonding pad' near3 'Copper' with 'Aluminum'</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/05 11:32
-	34	@ad<=20020109 and CVC.as. and interconnect	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/08/05 11:34
	1	(#62222E0#) PN	DERWENT; IBM_TDB USPAT	
		("6333559").PN.		2003/08/05 11:38
_	0	(("5785236") or ("6197613") or ("6162652") or ("6555759")).PN.	USPAT USPAT	2003/08/05 11:40 2003/08/05
_	. 0	"2002/0164840"	USPAT	11:41 2003/08/05
-	2	"20020164840"	USPAT; US-PGPUB;	11:42 2003/08/05 11:42
			EPO; DERWENT;	1
<u>-</u>	2	"20010035452"	IBM_TDB USPAT; US-PGPUB;	2003/08/05
		·	EPO; DERWENT;	
_	2	"20020047218"	IBM_TDB USPAT; US-PGPUB;	2003/08/05 11:43
			EPO; DERWENT;	
_	4	"2003012776"	IBM_TDB USPAT; US-PGPUB;	2003/12/22 11:23
			EPO; JPO; DERWENT;	
**	2	"20030127716"	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/12/22 11:23
			DERWENT; IBM_TDB	
-	0	@ad<=20020109 and 'wiring bonding pad' and 'intermetal dielectric' and 'metal layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/12/22
-	0	@ad<=20020109 and 'wiring bonding pad'	IBM_TDB USPAT;	2003/12/22
		and 'intermetal dielectric'	US-PGPUB; EPO; JPO; DERWENT;	12:04
-	209	@ad<=20020109 and 'wiring bonding pad'	IBM_TDB USPAT; US-PGPUB;	2003/12/22 12:10
,			EPO; JPO; DERWENT; IBM_TDB	
-	22	@ad<=20020109 and 'wiring bond pad'	USPAT; US-PGPUB; EPO; JPO;	2003/12/22 12:04
		·	DERWENT; IBM TDB	

· -	44	@ad<=20020109 and 'copper' and 'bonding	USPAT;	2003/12/22
		pad' and 'IMD'	US-PGPUB; EPO; JPO;	12:48
			DERWENT;	
		0-14 20020100 - 1 1 1 1 1 1 1 1 1	IBM_TDB	0000/10/00
-	40	<pre>@ad<=20020109 and 'copper' and 'bond pads' and 'IMD'</pre>	USPAT; US-PGPUB;	2003/12/22
		· ·	EPO; JPO;	
			DERWENT;	
_	69	@ad<=20020109 and 'bond pads' and 'IMD'	IBM_TDB USPAT;	2003/12/22
		France Sites	US-PGPUB;	12:54
			EPO; JPO; DERWENT;	
			IBM TDB	
-	107	@ad<=20020109 and 'bond pads' same	USPĀT;	2003/12/22
		'mechanical stress'	US-PGPUB; EPO; JPO;	12:59
			DERWENT;	
		0 14 20022100 111 11	IBM_TDB	0000/10/00
_	108	<pre>@ad<=20020109 and 'bonding pad' same 'mechanical stress'</pre>	USPAT; US-PGPUB;	2003/12/22 12:59
			EPO; JPO;	
			DERWENT;	
_	1	@ad<=20020109 and 'bond pads' same	IBM_TDB USPAT;	2003/12/23
	_	'buffer layer' same 'bonding layer'	US-PGPUB;	09:54
		·	EPO; JPO; DERWENT;	
			IBM TDB	
-	1	@ad<=20020109 and 'bonding pad' same	USPAT;	2003/12/23
		'buffer' same 'bonding layer'	US-PGPUB; EPO; JPO;	09:57
-			DERWENT;	
		0.14.00000100 1.147774 1.14	IBM_TDB	2002/12/22
_	13	<pre>@ad<=20020109 and 'UBM' and 'bond pads' and 'buffer' and 'bonding'</pre>	USPAT; US-PGPUB;	2003/12/23
			EPO; JPO;	
			DERWENT; IBM TDB	
_	497	@ad<=20020109 and 'bond pads' and 'EDS'	USPAT;	2003/12/23
		-	US-PGPUB;	10:12
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	2	@ad<=20020109 and 'bond pads' with 'EDS'	USPAT; US-PGPUB;	2003/12/23
<u> </u>			EPO; JPO;	10.03
			DERWENT;	
_	315	chou.in. and taiwan	IBM_TDB USPAT;	2003/12/23
]	onoa.ii. ana caiwan	US-PGPUB;	10:06
			EPO; JPO;	
			DERWENT; IBM TDB	
-	0	chou-kuo.in.	USPAT;	2003/12/23
			US-PGPUB; EPO; JPO;	10:04
			DERWENT;	
			IBM_TDB	0000/10/00
_	25	kuo-yu.in.	USPAT; US-PGPUB;	2003/12/23 10:06
			EPO; JPO;	-0.00
			DERWENT;	
_	1	@ad<=20020109 and 'single layer' near	IBM_TDB USPAT;	2003/12/23
	1	'wiring bond pad'	US-PGPUB;	10:13
		,	EPO; JPO;	
			DERWENT; IBM TDB	
L .	L		TDEL TOD	

_	22	@ad<=20020109 and 'wiring bond pad'	USPAT;	2003/12/23
			US-PGPUB;	10:13
			EPO; JPO;	
			DERWENT;	
			IBM TDB	[